


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C32-DFMC6TG	CGZW*2432AKA	A	P1C7	2017-03-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2X3X0.6	8	No lead	
Comment	Package : ZW UDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CGZW*2432AKA				5.999999.0	100.0062.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.486	mg	supplier	die	Silicon (Si)	7440-21-3		0.462	mg	950617	28875
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	4115	125
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	4115	125
				supplier	Passivation	Silicon Oxide	7631-86-9		0.020	mg	41152	1250
Lead-frame	M-011 Other inorganic materials	3.007	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.918	mg	970270	182353
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23358	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	225
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	3980	748
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	255	48
				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	106	20
Die Attach	M-011 Other inorganic materials	0.335	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.229	mg	684000	14341
				supplier	glue or soft solder	methylene diacrylate	42594-17-2		0.084	mg	250000	5242
				supplier	glue or soft solder	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.010	mg	30000	629
				supplier	glue or soft solder	Polymer of Polybutadiene + Anhydride	Proprietary		0.010	mg	30000	629
				supplier	glue or soft solder	Palladium (Pd)	7440-05-3		0.000	mg	1000	21
Wires	M-011 Other inorganic materials	0.021	mg	supplier	glue or soft solder	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.002	mg	5000	105
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.021	mg	990000	1324
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.000	mg	10000	13
Encapsulation	M-011 Other inorganic materials	12.150	mg	supplier	Moulding Compound	silica vitreous	60676-86-0		10.645	mg	876112	665350
				supplier	Moulding Compound	Phenolic resin	Proprietary		0.572	mg	47098	35768
				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.448	mg	36859	27992
				supplier	Moulding Compound	carbon black	1333-86-4		0.025	mg	2048	1555
				supplier	Moulding Compound	Zinc hydroxide	20427-58-1		0.012	mg	1024	778
Finishing	M-011 Other inorganic materials	0.000	mg	supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.448	mg	36859	27992
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.000	mg	916800	7
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0